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2 mil Polyimide Tape 2B-series

GENERAL DESCRIPTION

This tape is manufactured from 2.0 mil thick Polyimide backing material with 1.5 mils of high temperature silicone pressure sensitive adhesive.

APPLICATIONS

This tape is constructed to fill the requirements of a high performance polyimide backing material. It is often used for applications that require holding, insulating, or wrapping. It is also chosen for gold finger protection during wave solder applications.

FEATURES/BENEFITS

This tape has excellent mechanical and electrical properties as well as a high conformability. It offers outstanding resistance to cut-through, and is impact and abrasion resistant. It also offers excellent dielectric strength, while the burning of the adhesive forms a non-conductive ash. This material meets the Underwriters Laboratories, Inc. Guide OANZ2 and File #E51201 specifications with a 180°C temperature rating, and it complies with UL510 for a flame retardant. The polyimide backing meets MILP- 46112B. It currently uses DuPont Kapton® brand polyimide.

PHYSICAL PROPERTIES

Adhesive Type	Silicone
Total Thickness	.0035 in.
Backing Thickness	.0020 in.
Adhesive Thickness	.0015 in.
Adhesion to Steel	25 oz/in
Break Strength	50 lbs/in.
Dielectric Strength	10000 volts
Elongation	75 % at break
Operating Temperature	-100 TO 500 °F
Color	Amber

NOTE:

1. When applying pressure sensitive adhesive films to any surface, be sure that the surface is free from oil or other surface contaminants such as powder, dust, or release agents. Adhesive performance should be carefully checked when used on substrates containing plasticizers.
2. The above values are "Typical Values" which have a nominal range about them and are not intended for specification purposes.